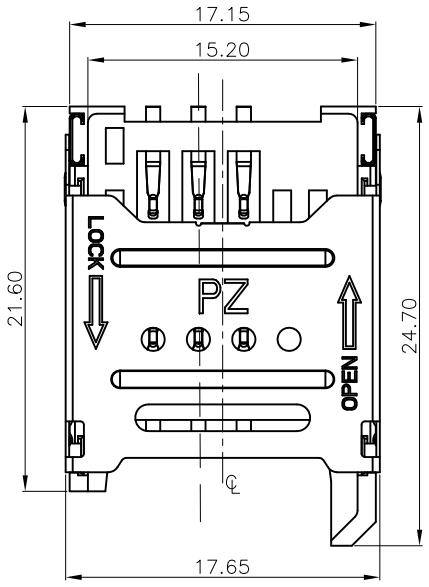
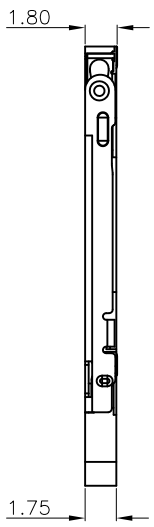
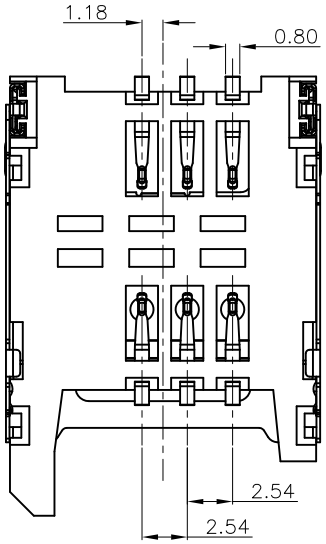
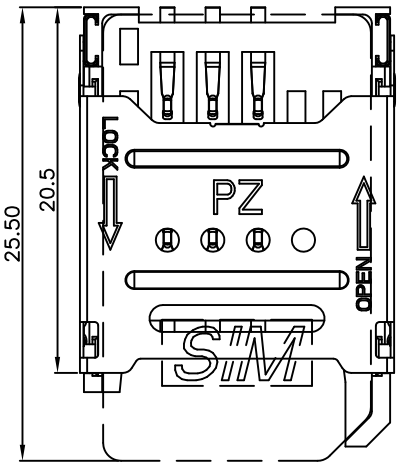
CAD GENERATED DRAWING. DON'T CHANGE BY HAND.

REV.	ECN NO.	DESCRIPTION	DESIGN	DATE
A0		Initial Release	Jason	11/03/01

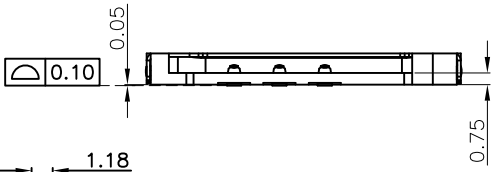


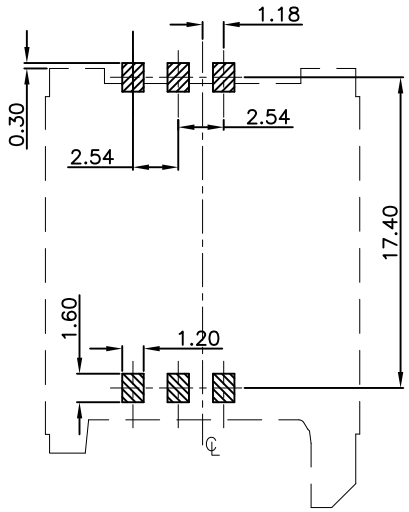






STATE OF LOCK





PCB LAYOUT
T±0.05

XNTSM07- 6 K 5

- 5 — PLATING 1~3u" AU
- K — BLACK
- 6 — 6PIN
- XNTSM07 — 掀盖式SIM卡

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DIM	TOL	DIM	TOL
X.	±0.30	X.°	± 2°
.X	±0.20	.X°	± 1°
.XX	±0.15	.XX°	± 0.5°
.XXX	±0.10		

PART NO.: XNTSM076K5

TITLE: 掀盖式SIM CARD PACKING DWG,

APPD: Simon 2011/03/01

DWG NO.: XNTSM076K5-H180

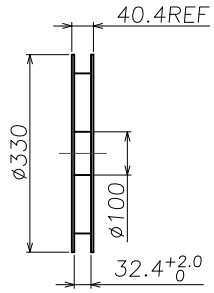
CHKD:

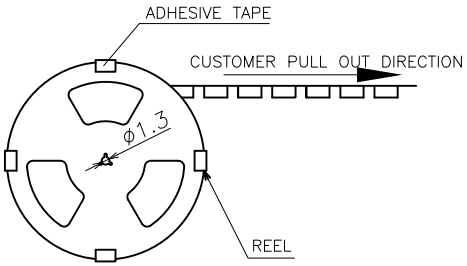
DR: Jason 2011/03/01

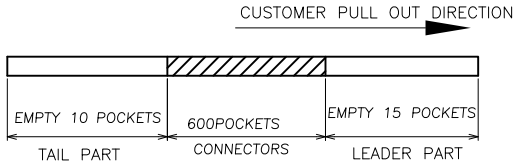
UNITS	SCALE	SHEET	REV.
mm	1:1	1/2	A0

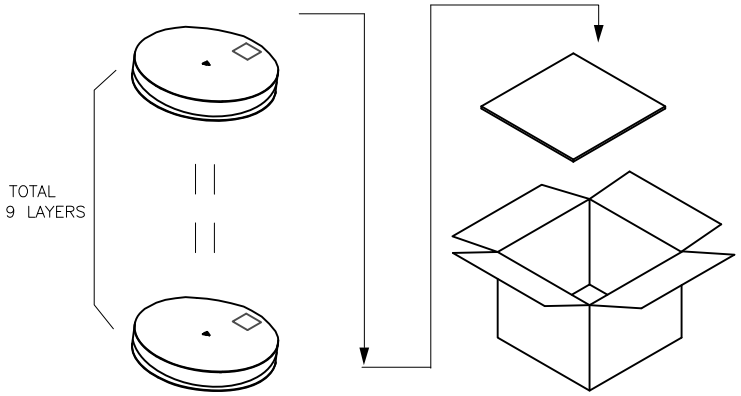
CAD GENERATED DRAWING. DON'T CHANGE BY HAND.

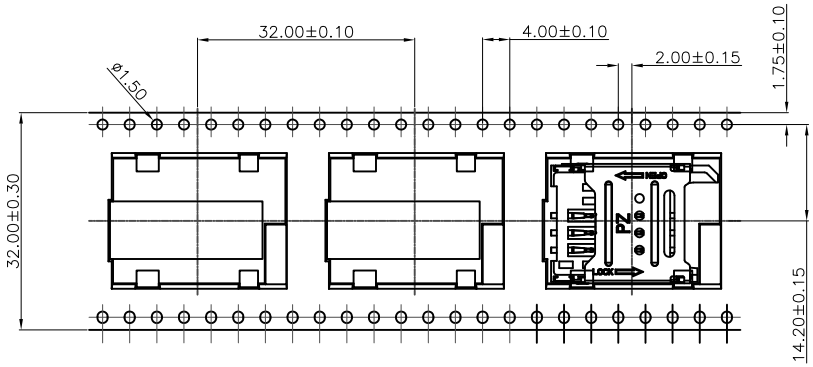
REV.	DESCRIPTION	DESIGN
A0	Initial Release	Simon











NOTES:
1.PRIMARY PACKING:20.0M/600PCS/REEL;
2.SECONDARY PACKING: 9 REELS/CARTON(5400 PCS/CARTON);

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DIM	TOL	DIM	TOL
X.	±0.30	X.°	± 2°
.X	±0.20	.X°	± 1°
.XX	±0.15	.XX°	± 0.5°
.XXX	±0.10		

PART NO.: XNTSM076K5

TITLE: 掀盖SIM CARD PACKING DWG,

APPD: Simon 2011.03.01

DWG NO.: XNTSM076K5H180

CHKD:

DR: huliyan 2011.03.01

UNITS	SCALE	SHEET	REV.
mm	N/A	2/2	A0

1. SCOPE [适用范围]

1.1. CONTENTS [内容]

The specification covers performance, tests and quality requirements for SIM CARD connector. [本规范包含了 SIM CARD 连接器产品的性能、测试方法、品质保证要求]

1.2. QUALIFICATION [条件]

Tests are to be performed by the procedures stated in this specification. All inspections shall be conducted using the inspections plan for this product and product drawing.

[测试时应按此规范规定的程序执行，所有的检验应在使用相应的检验计划和产品图纸下进行]

2. APPLICABLE DOCUMENTS [适用文件]

Unless otherwise specified, the latest edition of the document applies. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

[除非另有规定，适用文件的最新版本；当此规范的要求与产品图纸不相符时，则以产品图纸为准；当此规范的要求与参考文件不相符时，则以此规范为准]

3. REQUIREMENTS [要求]

3.1. DESIGN AND CONSTRUCTION [设计与构造]

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing. [产品的设计、构造和物理尺寸应与适用的产品图纸相符]

3.2. MATERIALS [材料]

A. Housing：Thermoplastic Plastic,LCP+30%GF, Color: Black
[主体：热塑性塑胶，LCP+30%GF，颜色：黑色]

B. Contact： Phosphor bronze,
Finish： Ni underplating overall, Gold plating on contact area ,
[端子：磷铜； 电镀：镍打底，端子接触区镀金]

C. Shell： Stainless Steel,
Finish： Ni underplating overall, all plating Sn ,
[铁壳：不锈钢； 电镀：镍打底，刷金]

3.3. RATINGS [额定值]

A. Rated Voltage ：15V AC [额定电压：15V AC]

B. Rated Current ：0.5A Max (per pin) [额定电流：每个端子 0.5A 的最大电流]

C. Operating temperature： -40℃ to +85℃ [使用温度范围：-40℃ to +85℃]

3.4. PERFOMANCE REQUEIREMENT AND TEST DESCRIPTION [性能要求及测试描述]

The product shall be designed to meet the electrical, mechanical and environmental performance requirements specified in Figure 1. Unless otherwise specified, all tests shall be performed at ambient environmental conditions.

[产品的设计应符合表 1 中规定的电气、机械及环境性能要求。除非另有规定，所有的测试应在室内环境下进行]

Working position normal force: 0.3N/pin Min.(at contact deflection 0.35mm).
工作位置的端子弹力大小: 0.3N/pin Min.(端子下压 0.35mm 时)
Recommended contact working range: 0 to 0.10mm from housing top surface.
端子的推荐工作范围：从 housing 上表面到上表面以上 0.10mm 的范围内

3.5. PERFORMANCE REQUIREMENT AND TEST PROCEDURES

[性能要求及测试程序摘要]

TEST ITEM [测试项目]	REQUIREMENT [测试要求]	TEST CONDITION [测试方法]
Examination of Product [外观检查]	Meet the requirements of product drawing. No physical damage. [与产品图纸相符,无物理损坏]	Visual inspection [目视] (IEC 512-2, test 1a)
ELECTRICAL PERFORMANCE		
Contact Resistance [接触电阻]	30 mΩ Max. (Initial) 100 mΩ Max. (Final) [初始最大 30 毫欧,试验后最大 100 毫欧]	Mated connector, measure by dry circuit, 20mV Max, current 100mA. [配合连接器,在电压为 20mV Max, 电流为 100mA 的情况下进行测试] (IEC 512-2, test 2a)
Insulation Resistance [绝缘电阻]	1000MΩ Min.(Initial) [初期 1000 兆欧以上] 500MΩ Min.(Final) [试验后 500 兆欧以上]	Unmated connector, apply 500V DC between adjacent terminals. [未配合连接器,在相邻端子间应用 500V DC 的电压进行测试] (IEC 512-2, test 3a method C)
Dielectric Withstanding Voltage [耐电压]	No breakdown or flashover [无击穿，跳火发生]	Unmated connector, apply 500V AC for 1 minute between adjacent terminals. [未配合连接器,在相邻端子间应用 500V AC 的电压持续 1 分钟] (IEC 512-2, test 4a method C)
MECHANICAL PERFORMANCE		
Contact Normal Force [端子正向力]	0.30~0.70N /PIN [每 PIN 0.30~0.70N]	Measure contact pressure at contact point from housing top surface 0.10mm.(Speed:25±3mm/minute) [在距塑胶主体上表面 0.10mm 的位置，测量端子接触点的力] (测试速度：25±3mm/分)
Durability [耐久性]	Appearance: no damage.[外观无损坏] Contact Resistance: 100 mΩ Max. [接触电阻最大 100 毫欧] Contact Normal Force: 0.40N/pin Min. [端子正向力: 0.30N/pin Min.]	Mating connector up to 3000 cycles with card, at the speed rate of 10 cycles per minute. [以每分钟 10 个循环的速度，用卡配合连接器测试 3000 个循环] (IEC 512-5, test 9a)
Vibration [振动]	Appearance: no damage.[外观无损坏] No electrical discontinuity greater than 1 μ sec shall occur. [无 1 微秒或更长时间的断电现象发生]	Sweep time: 10-55-10Hz traversed in 1 minutes, Amplitude: 1.52 mm, Duration: 3 mutually perpendicular planes, 0.5h per plan(total 1.5h) [振动频率：10-55-10Hz，振幅：1.52mm，振动持续时间：3 个互相垂直相交的平面内各 0.5 小时(共 1.5 小时）] (IEC 512-4, test 6d)

Physical Shock [物理冲击]	Appearance: no damage. [外观无损坏] No electrical discontinuity greater than 1 μ sec shall occur. [无 1 微秒或更长时间的断电现象发生]	Accelerate Velocity：490m/s^2 （50g）， Waveform：Half-sine shock plus Duration：11msec 3 shocks each to mutually perpendicular axis (totally 18 shocks), passing DC 1mA current during the test. [加速度:490m/s^2 (50g),正弦半波波形,持续时间:11msec,每个互相垂直的轴方向3个冲击(共18个冲击),测试过程通 1mA 的直流电流] (IEC 512-4, test 6c)
ENVIRONMENTAL PERFORMANCE		
Thermal Shock [热冲击]	Appearance: no damage. [外观无损坏] Contact Resistance: 100 mΩ Max. [接触电阻最大 100 毫欧]	-40+/-2℃(30minute),+85+/-2(30minute), 5cycles; Transition time: 3 minute, Recovery time 1~2 h, [未配合连接器,-40℃ 30 分钟,+85℃ 30 分钟,以此为一循环进行 5 个循环,转换时间 3 分钟,恢复时间 1~2 h] (IEC 512-6, test 11d)
Humidity Test [湿度测试]	Appearance: no damage. [外观无损坏] Dielectric Withstanding Voltage: 100 V DC Min. Contact Resistance: 100 mΩ Max. Insulation Resistance :500MΩ Min. [耐压:100 V 以上,接触电阻:最大 100 毫欧,绝缘电阻:500 兆欧以上]	unmated Connector,40+/-2℃, 90~93%RH, 96hours, Recovery time1~2 h, [未配合连接器,温度 40+/-2℃,湿度 90~93% RH, 96 小时,恢复时间 1~2 h] (IEC 68-2-56)
Temperature Life (Heat Aging) [温度寿命(老化)]	Appearance: no damage. [外观无损坏] Contact Resistance: 100 mΩ Max. [接触电阻最大 100 毫欧]	Temperature:85+/-2℃, Duration:96hours. Recovery time 1~2 h, [温度 85+/-2℃,持续 96 小时,恢复时间 1~2 h] (IEC 68-2-2)
Salt Spray [盐雾]	No detrimental corrosion allowed in contact area and base metal exposed. [端子表面无腐蚀或露基材现象] Dielectric Withstanding Voltage: 100 V DC Min. Contact Resistance: 100 mΩ Max. Insulation Resistance :500MΩ Min. [耐压:100 V 以上,接触电阻:最大 100 毫欧,绝缘电阻:500 兆欧以上]	Subject mated connectors to 35+/-2 ℃ and 5+/-1% salt condition for 48hours. After test, rinse the sample with water and recondition the room temperature for 1 hour. [配合的连接器置于温度 35+/-2 ℃ ,盐水浓度为 5+/-1%, 持续 48 小时, 试验后样品用清水冲洗并室温下放置 1 小时] (EIA 364-26B, Condition B)
Solderability [沾锡性]	Wet Solder Coverage: 95% Min. [吃锡面 95%以上]	At a temperature of 235+/-5℃ for 5+/-0.5 seconds. [温度 235+/-5℃, 持续 5+/-0.5 秒] (IEC 68-2-20)
Resistance to Soldering Heat [耐焊接热]	No physical damage. [外观无损坏]	Pre Heat： 150~180℃, 90±30sec. Heat： 230℃ Min., 30±10sec. Peak Temperature： 260℃ for 10sec. (IEC 512-6, test 12d)

Figure 1 [表 1]

3.6. PRODUCT QUALIFICATION AND REQUALIFICATION TEST SEQUENCE

[产品质量测试顺序]

Test or examination	Test group					
	A	B	C	D	E	F
Examination of product	1, 11	1, 5, 8	1, 5, 7	1, 12	1, 3	1, 8
Contact resistance	2, 8	2, 4, 7	2, 4	2, 6, 9		2, 5
Insulation resistance	3, 9			3, 7, 10		3, 6
Dielectric withstanding voltage	4, 10			4, 11		7
Contact normal force	5, 7					
Durability	6					
Vibration		3				
Physical shock		6				
Thermal shock				5		
Humidity test				8		
Temperature life (Heat aging)			3			
Salt spray						4
Solderability					2	
Resistance to soldering heat			6			
Number of sample	4 PCS	4 PCS	4 PCS	4 PCS	4 PCS	4 PCS

Figure 2 [表 2]

NOTES：（a）Numbers indicate sequence in which tests are performed.

［表格中的数字为测试顺序］

（b）Discontinuities shall not take place in this test group, during tests.

［整个测试过程，群组里的每项测试连续进行］